

Figure 7

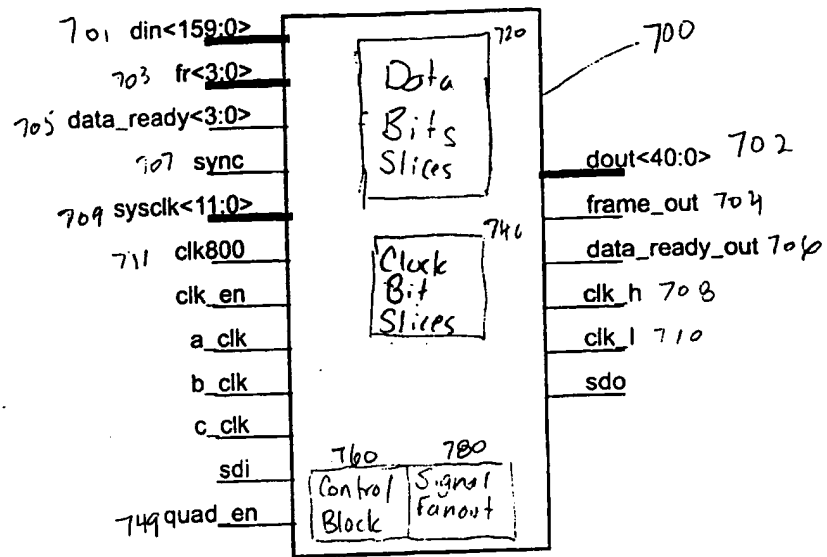


Figure 7A

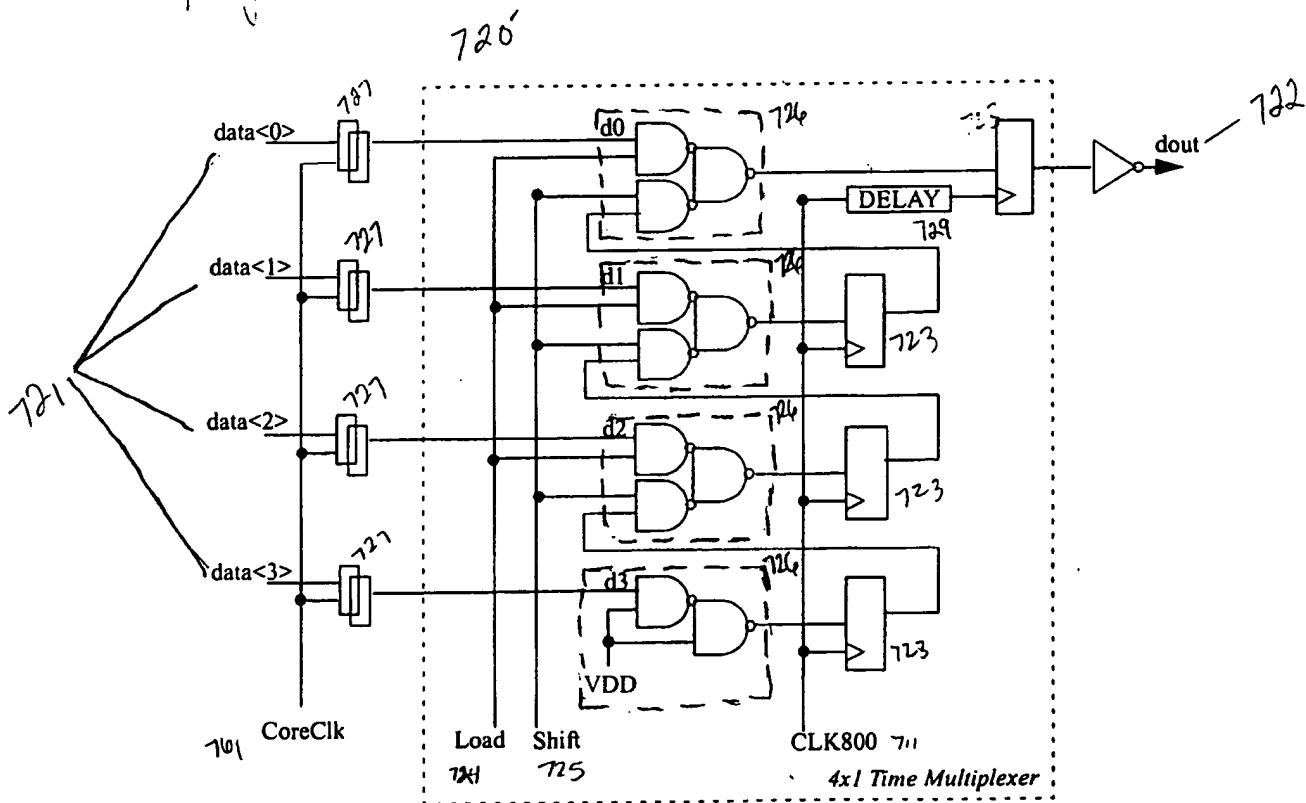


Figure 7B

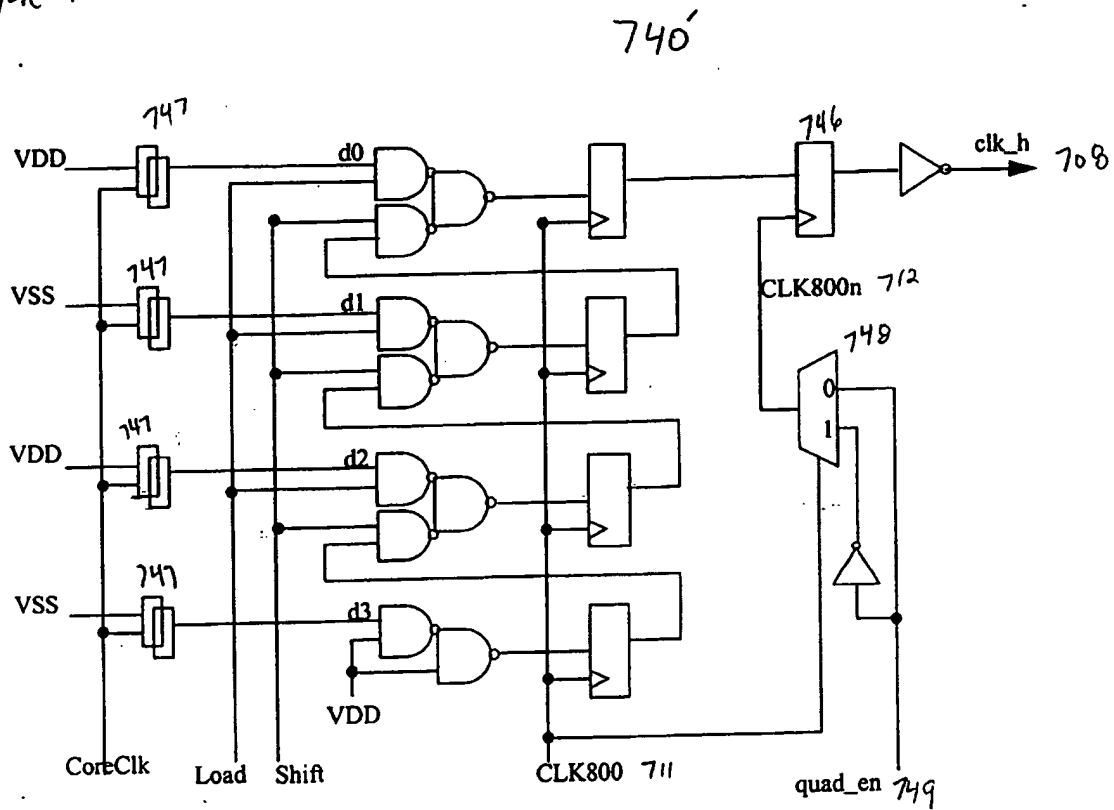


Figure 7C

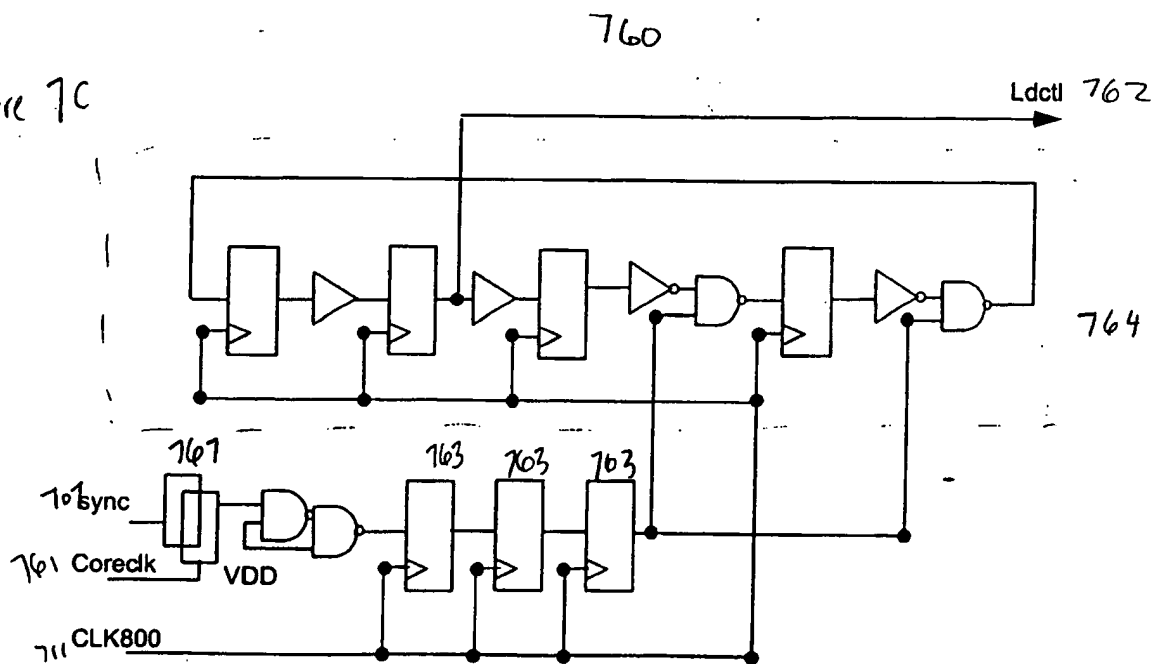


Figure 7D

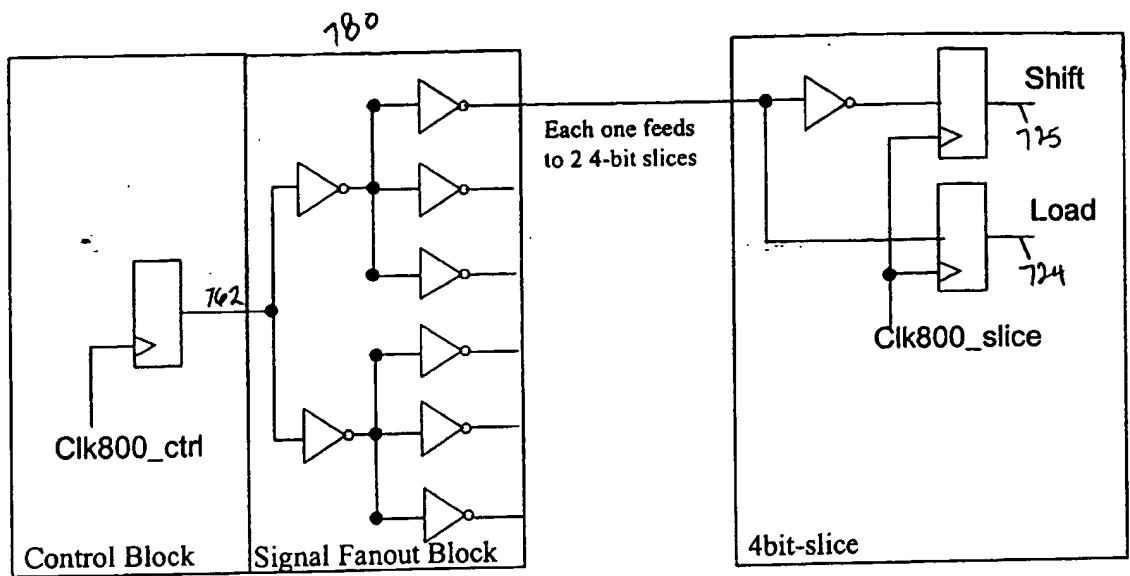


Figure 1E

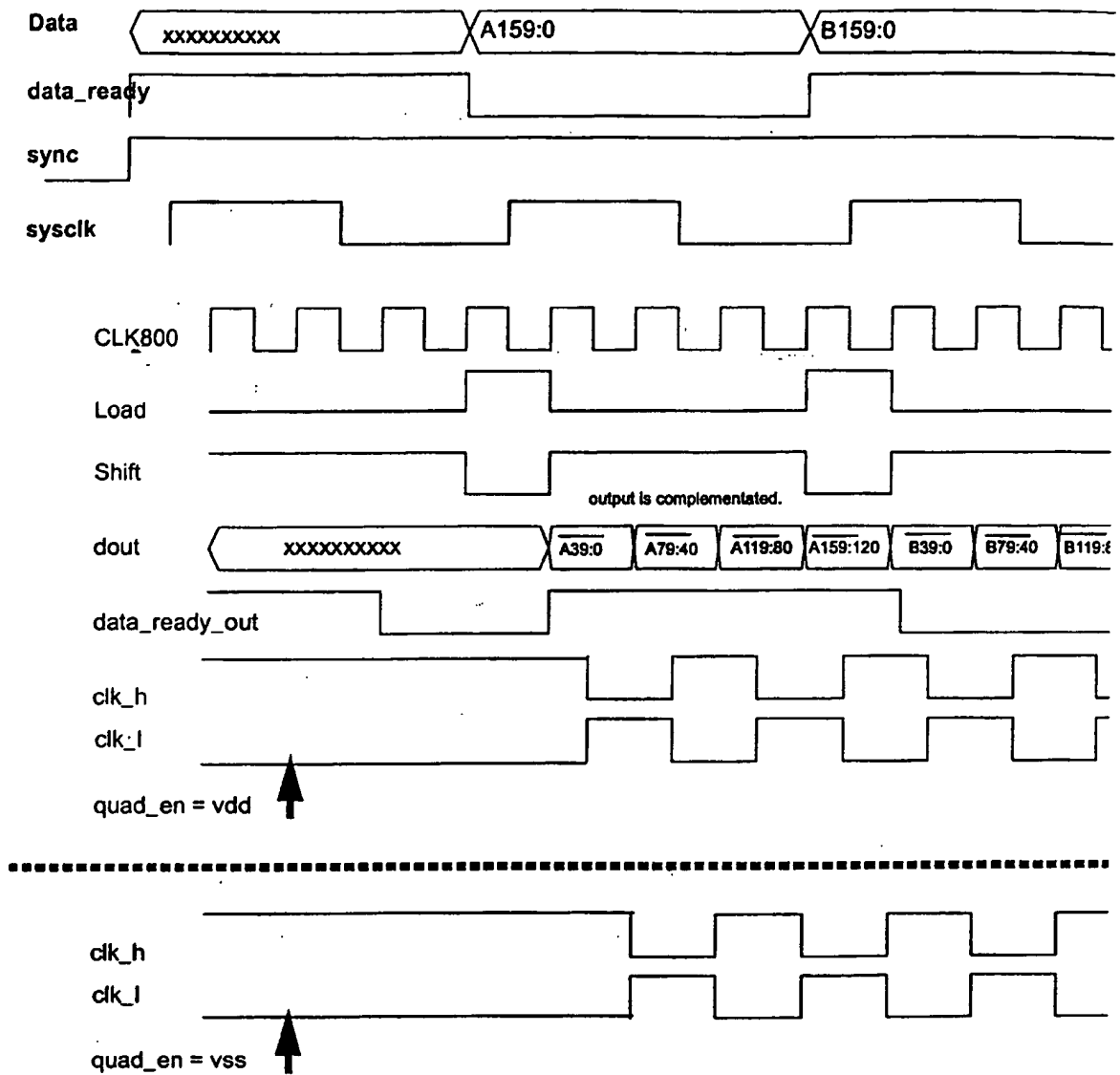
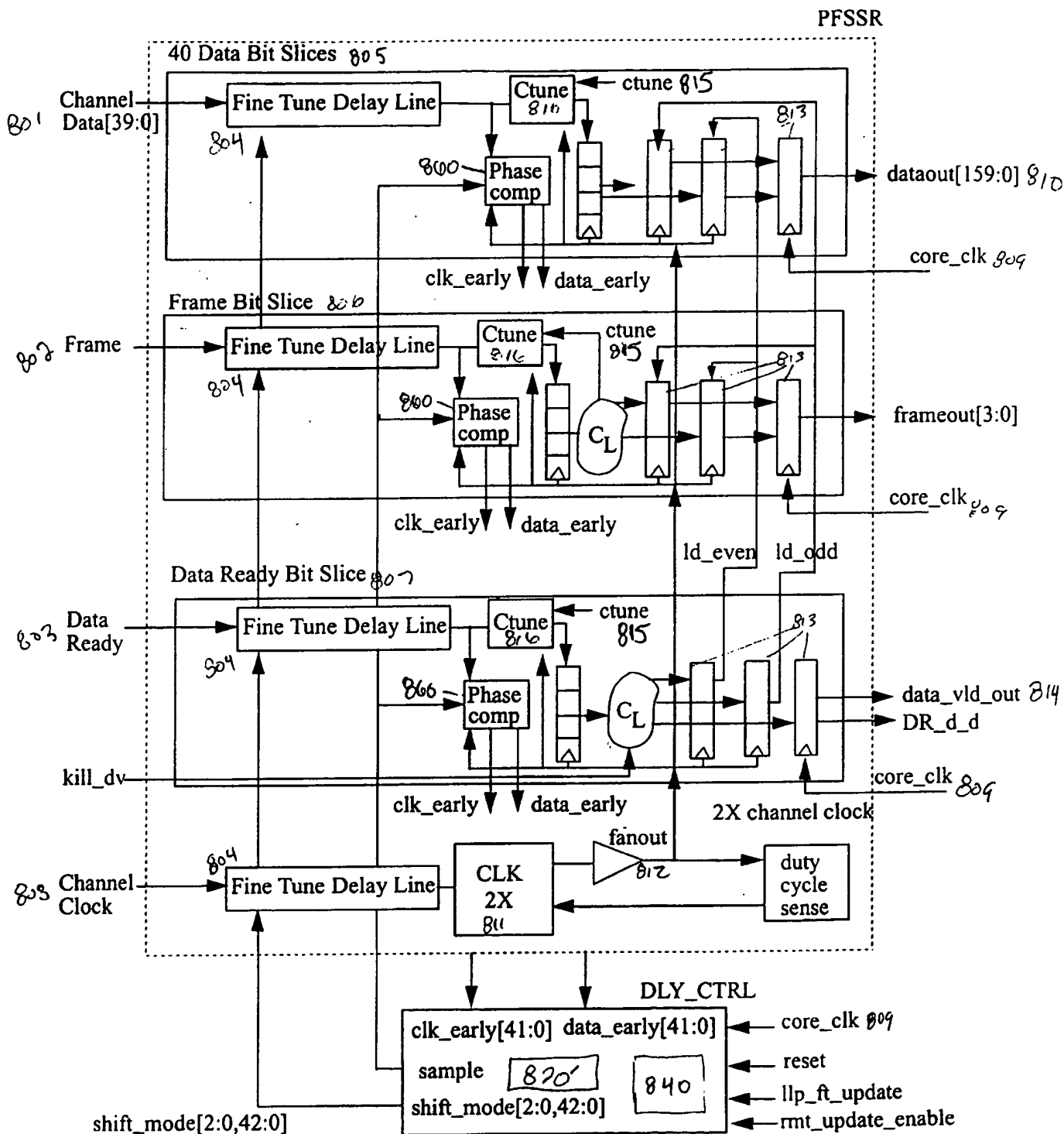


Figure 8

800



820

Figure 8A

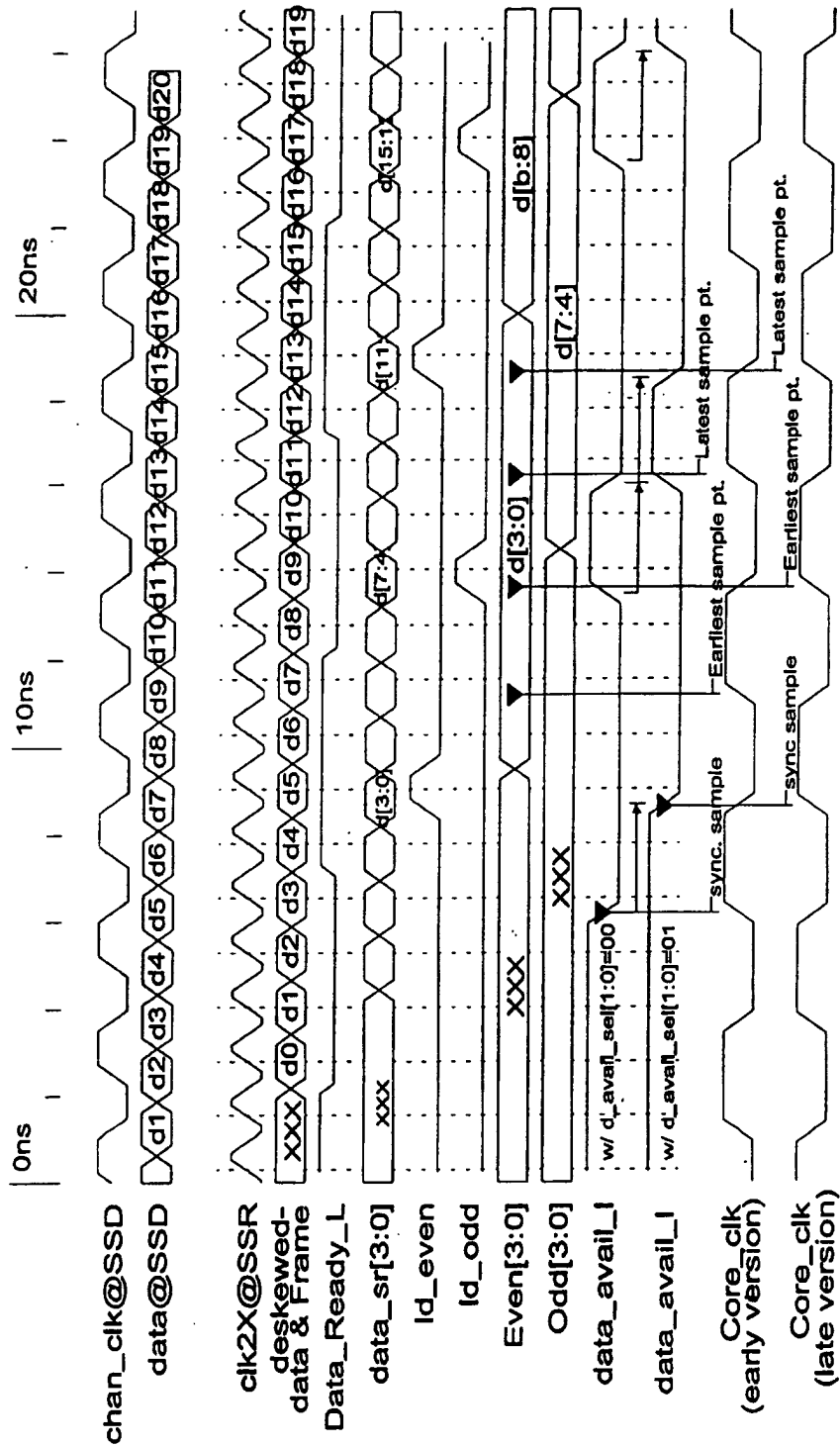


Figure 8B

840

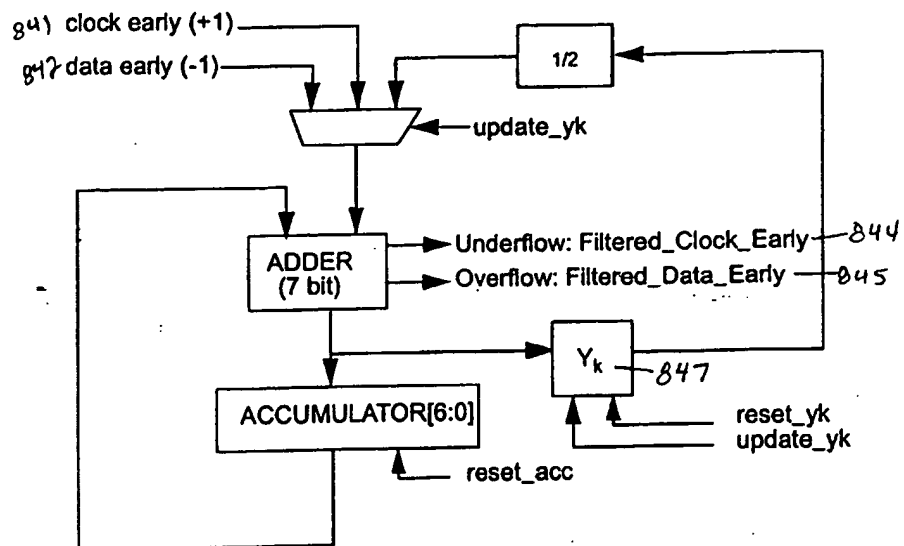


Figure 8c

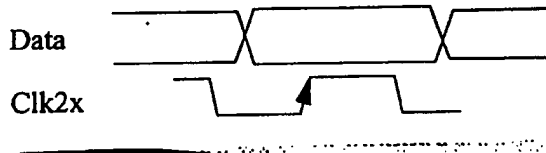
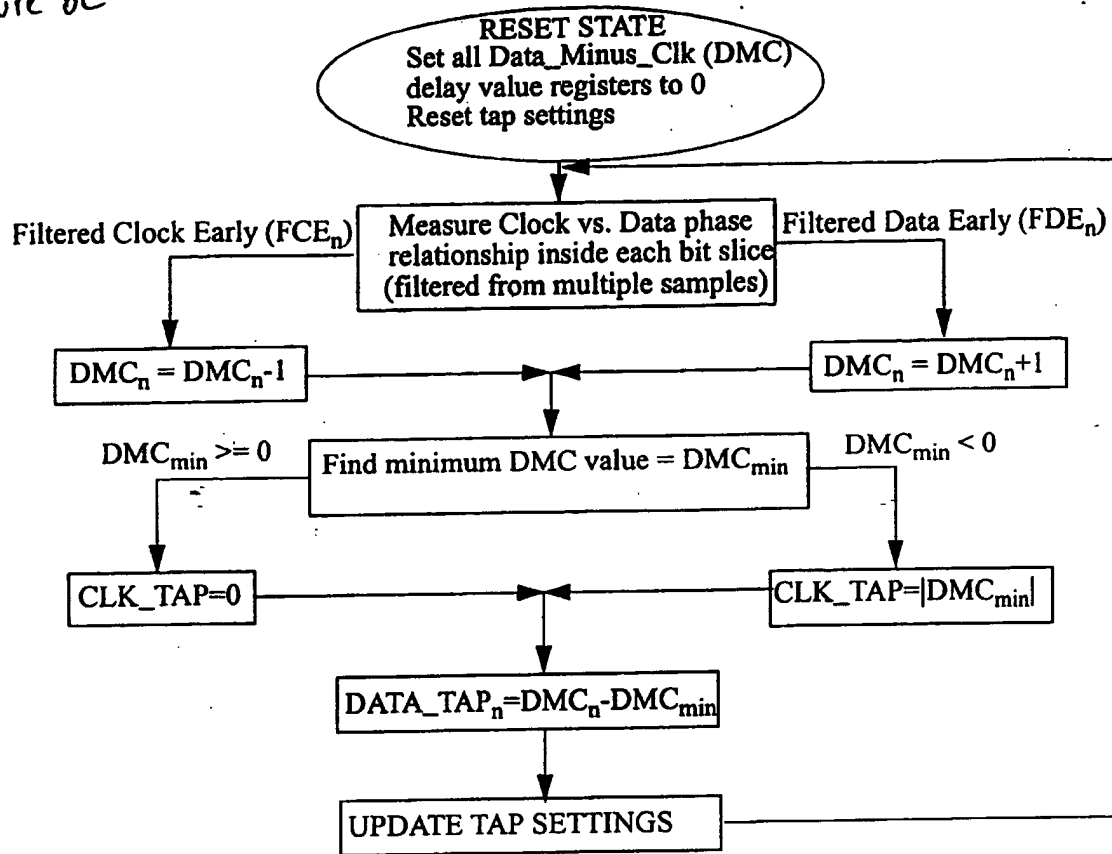


Figure 8d

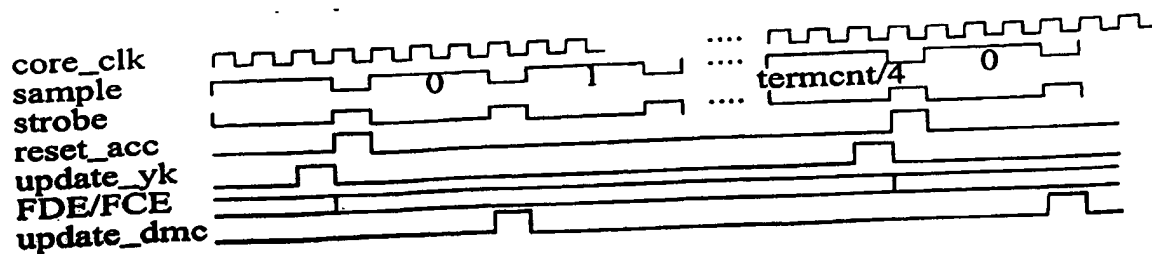
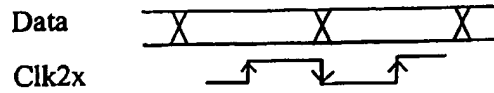
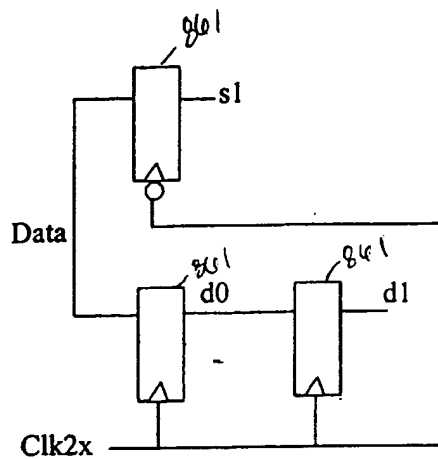


Figure 8E

860



Possible Samples - condition

d1	s1	d0	condition
0	0	0	steady 0 (no timing info.)
0	0	1	rising data (clk early)
0	1	0	(uncertain sample)
0	1	1	rising data (data early)
1	0	0	falling data (data early)
1	0	1	(uncertain sample)
1	1	0	falling data (clk early)
1	1	1	steady 1 (no timing info.)

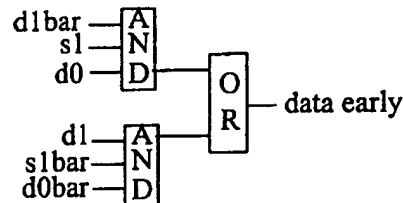
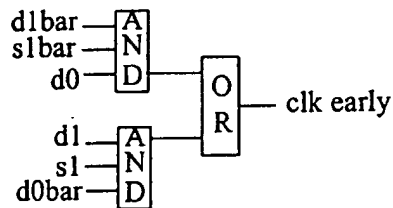


Figure 8F

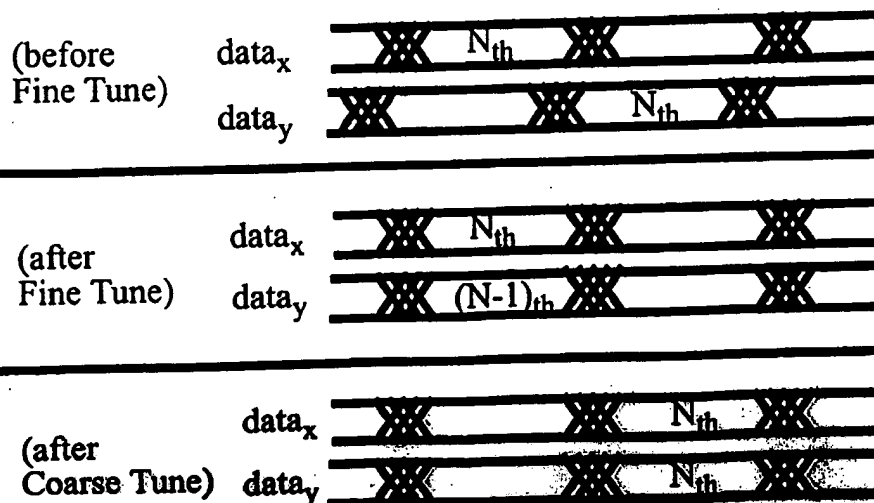


Figure 9

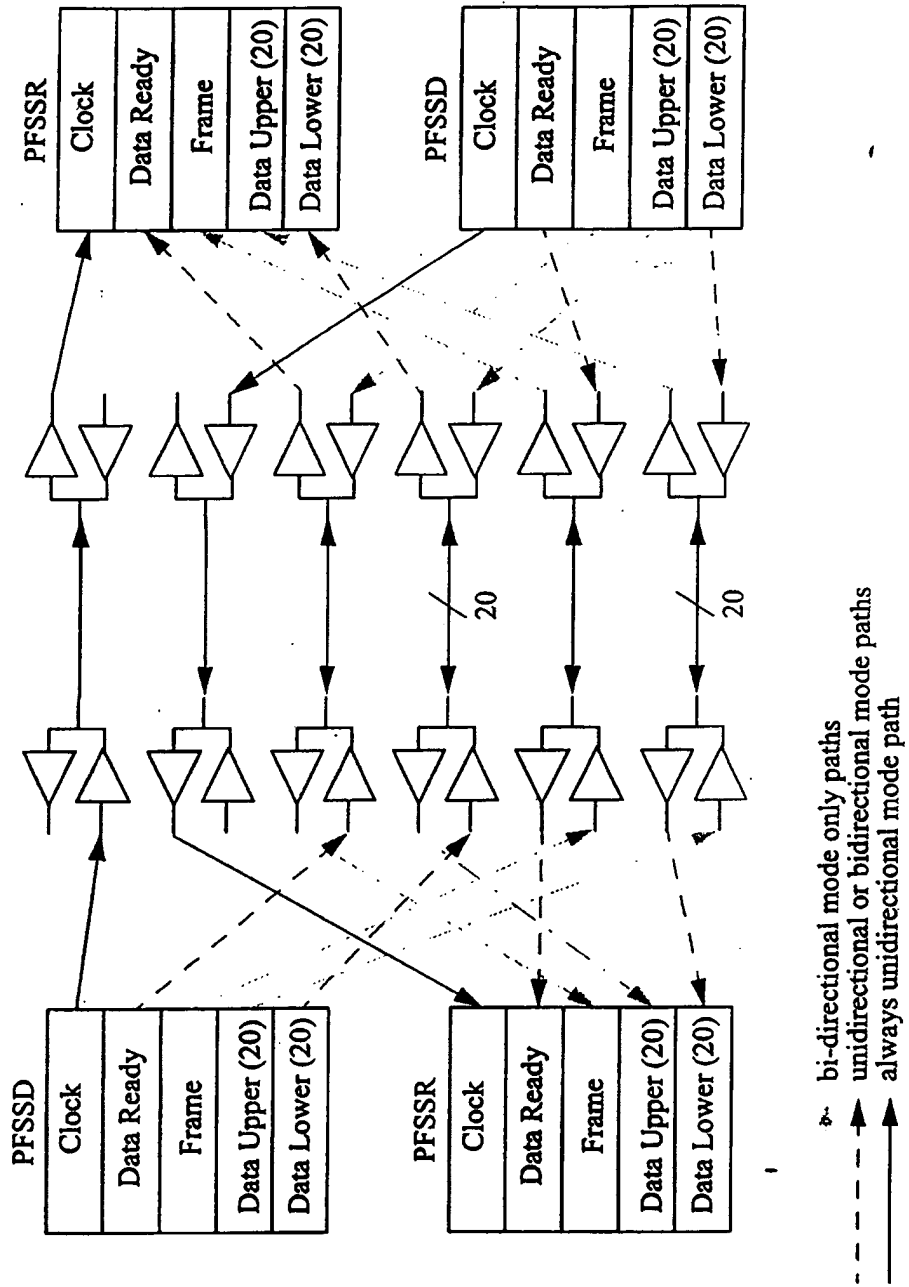


Figure 10

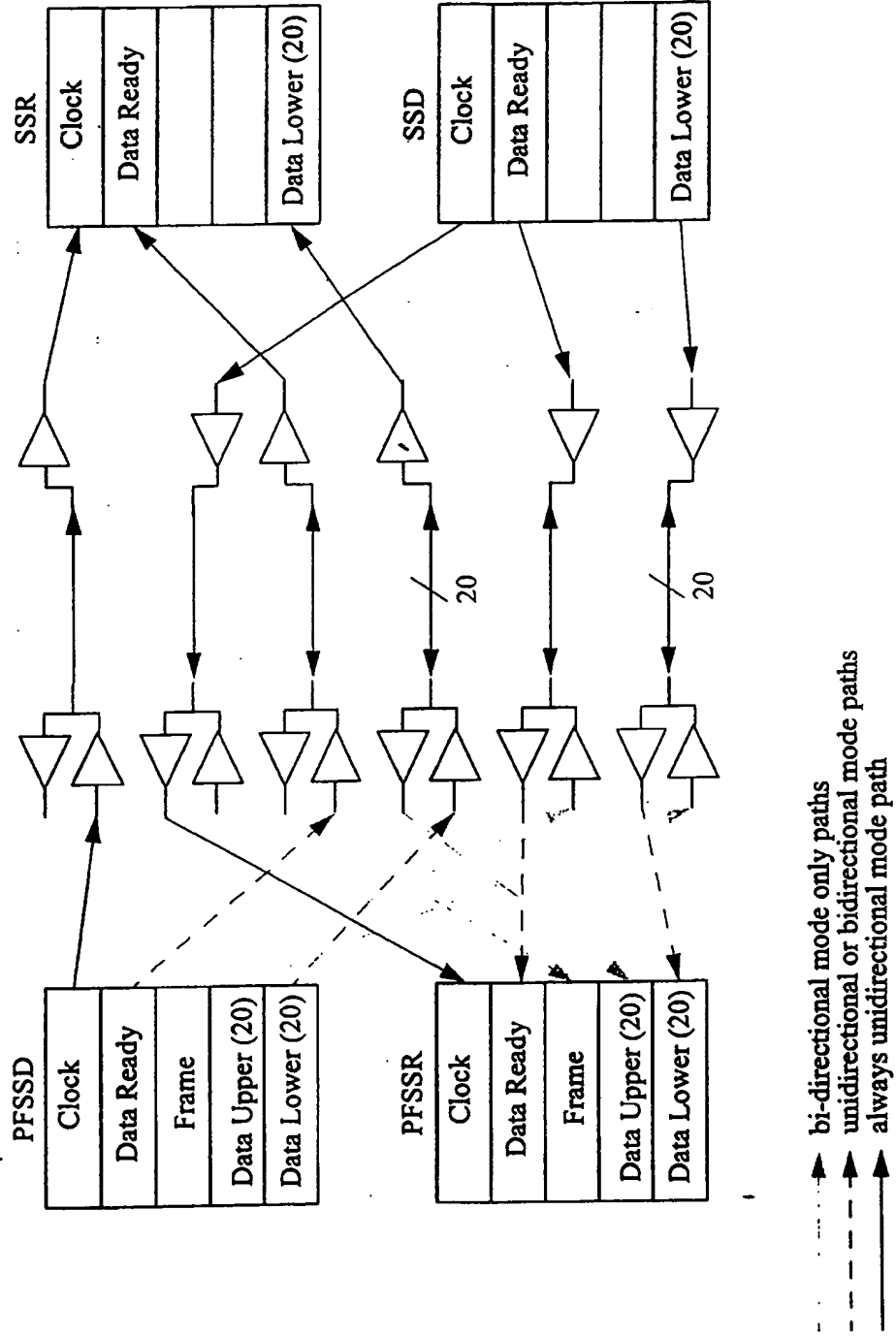


Figure 11

1100

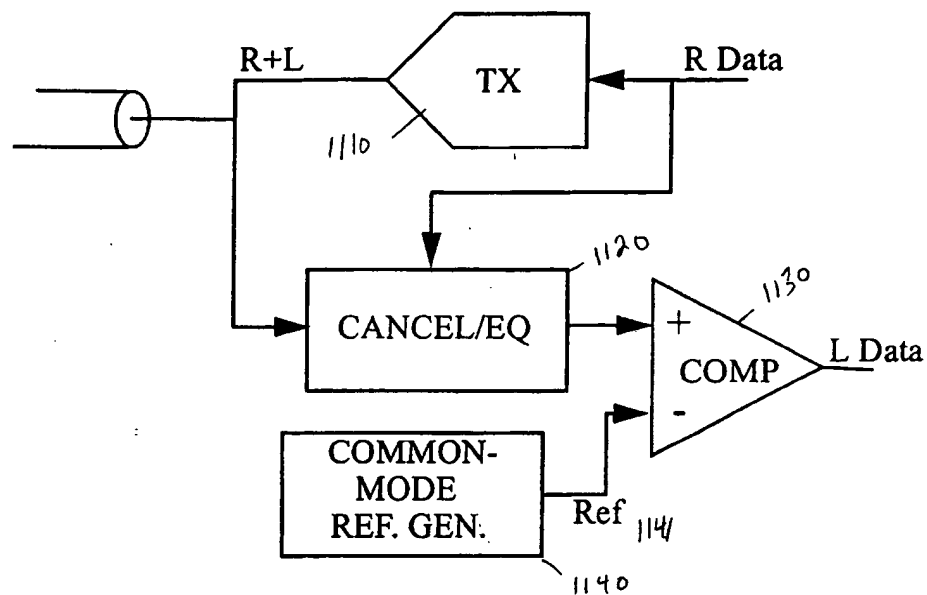


Figure 12

1200

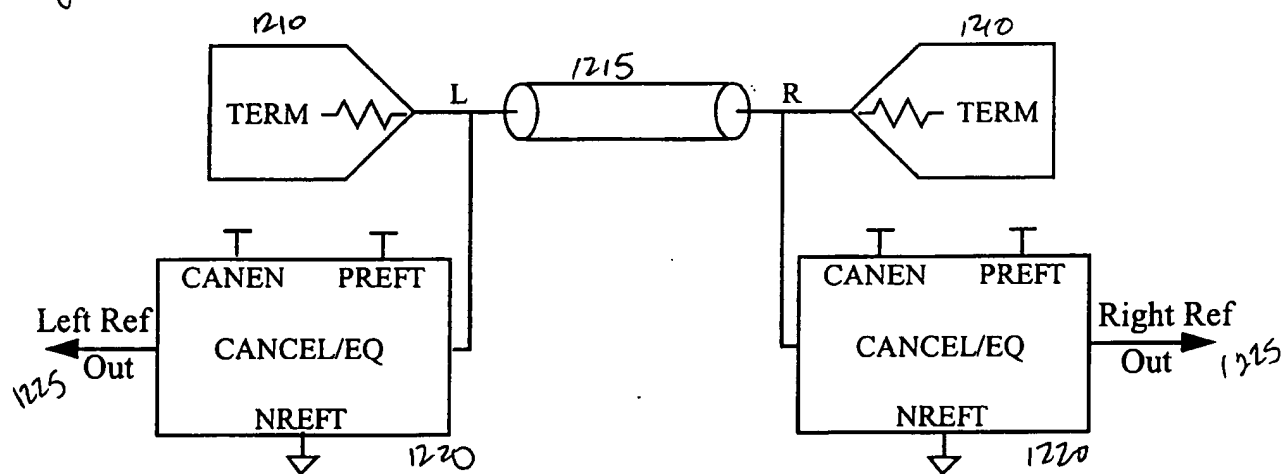


Figure 13

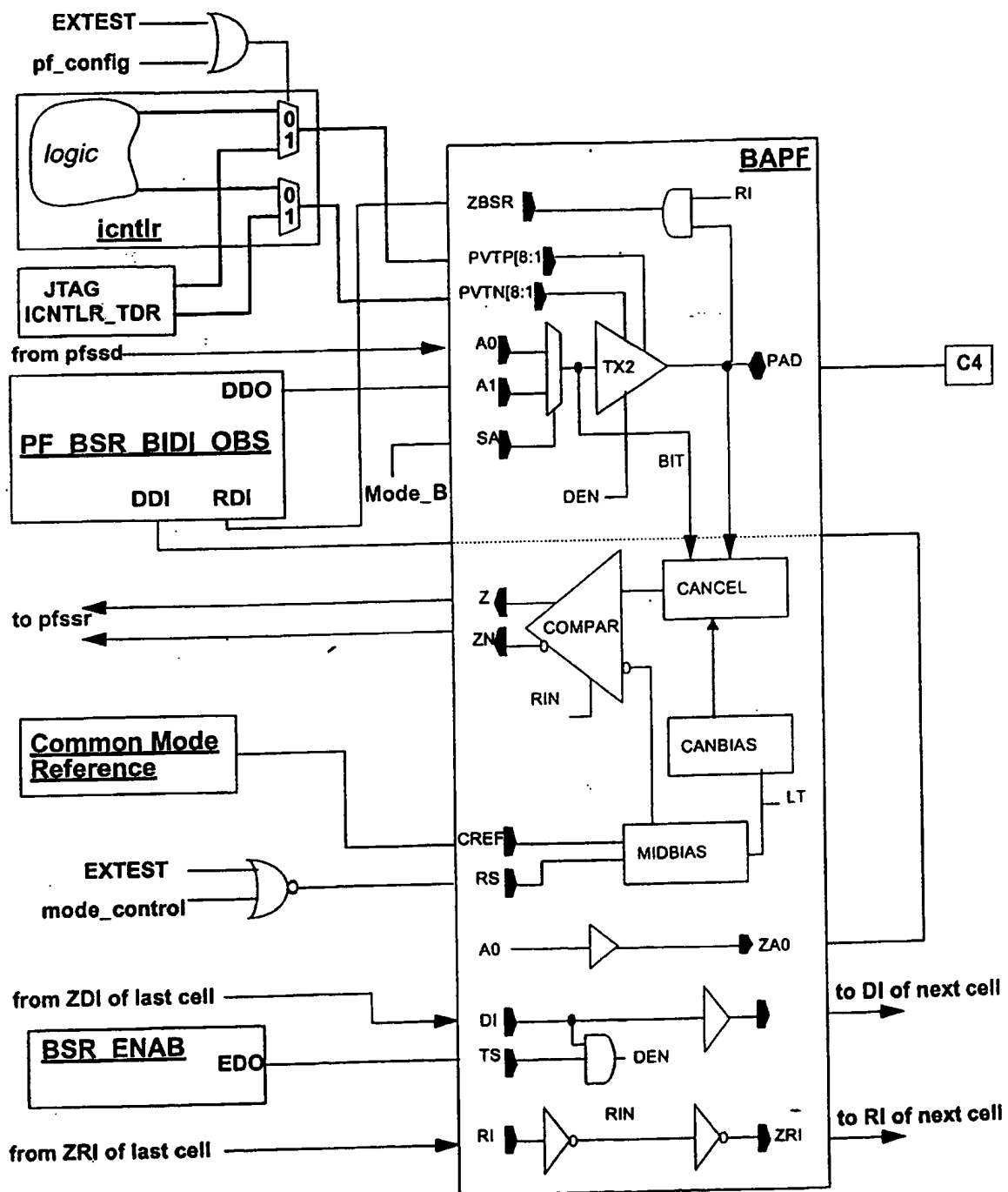


Figure 14

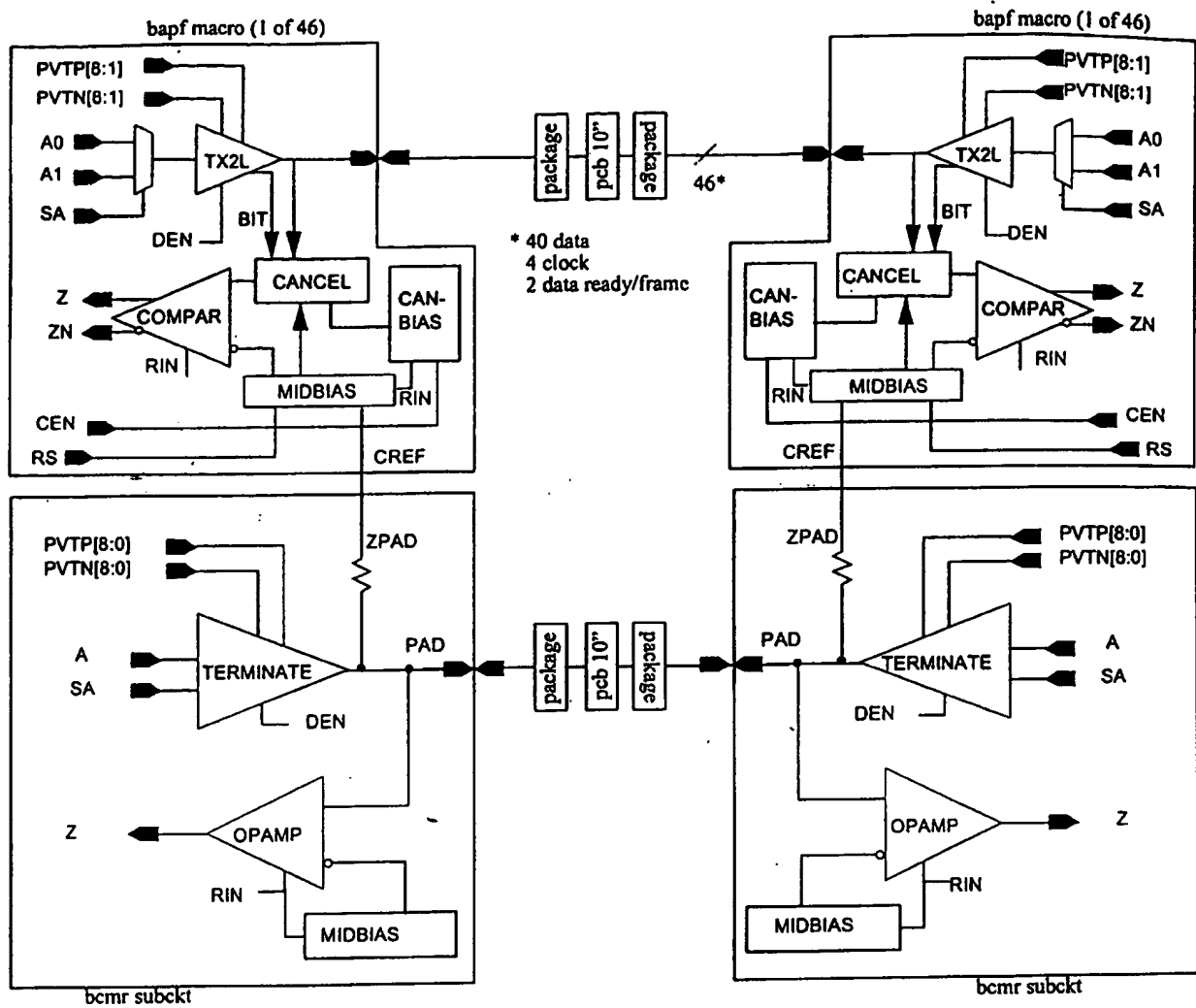
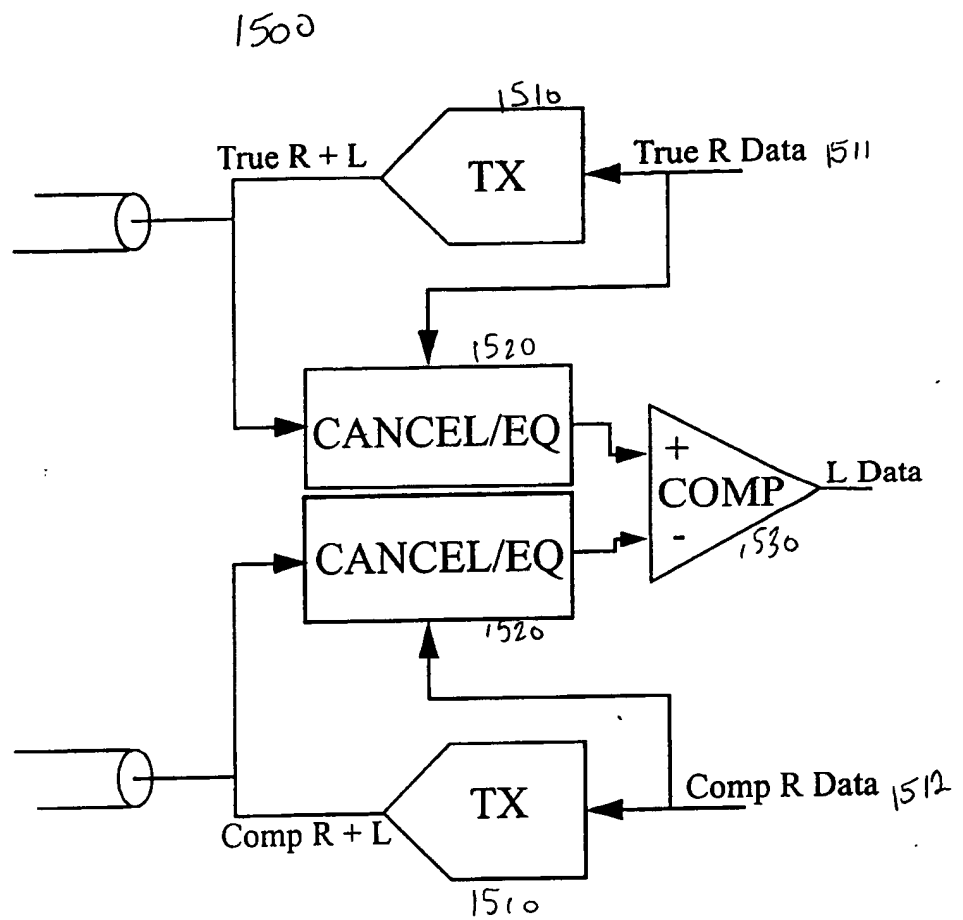
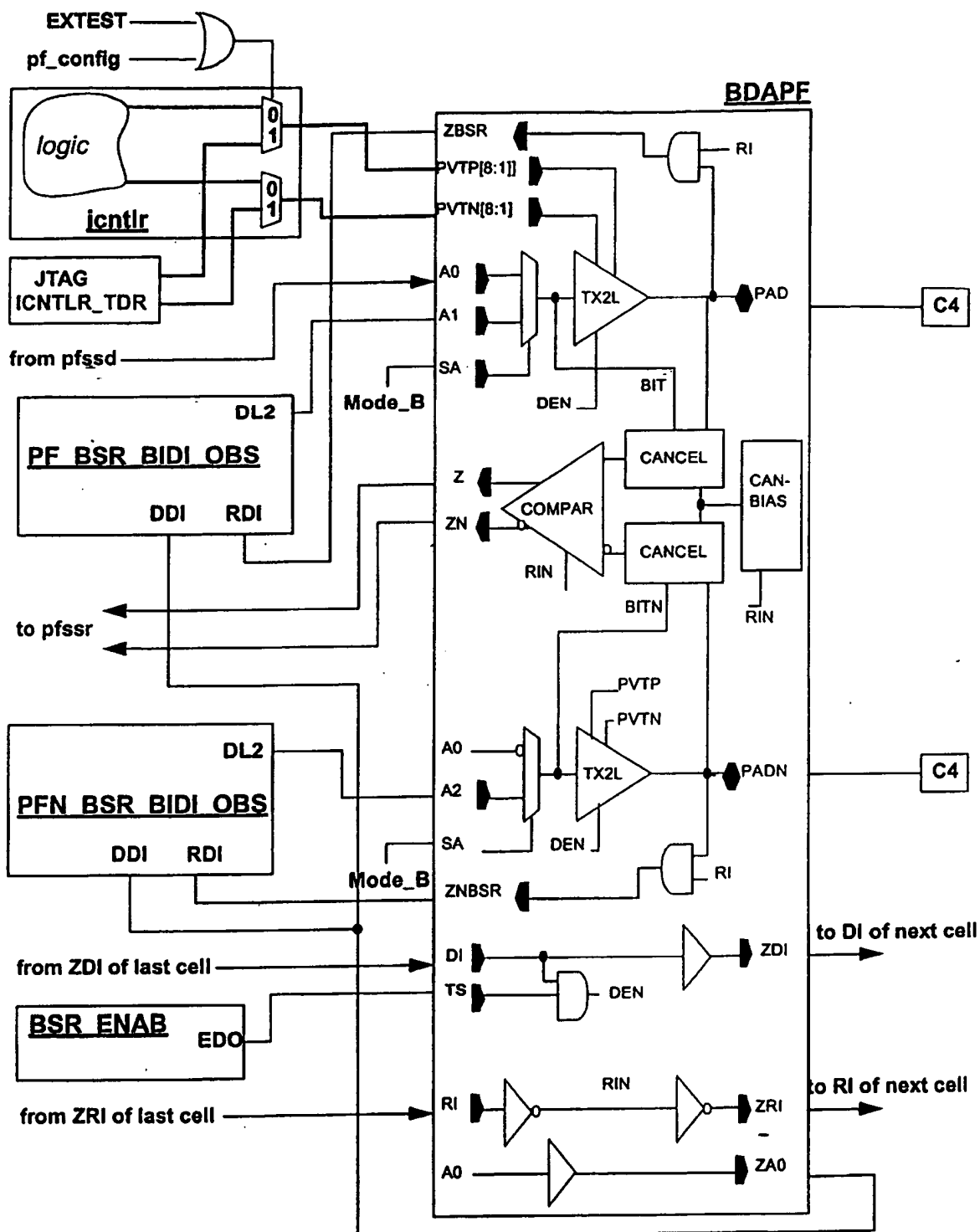


Figure 15





models used:

- package: gorepack6
- pcb: pcb_n4k6
- connector: mdr_6
- cable: dxn1948.rlc

BDAPF Macro (1 of 44)

Figure 1 consists of two parts. The left part is a schematic diagram of a cable assembly. It shows a PCB with two components, A and B. Component A is labeled as $12\ \Omega$ and component B is labeled as $0\ \Omega$. The PCB is connected to a cable assembly. The cable assembly has a central conductor connected to component A and a shield connected to component B. The shield is grounded. The right part is a cross-sectional view of the cable assembly. It shows the internal structure: Insulator, Cable Dock, Spring Gasket, PCB Internal Planes Grounded, Inner Shield, Inner Insulator, Outer Jacket, Outer Shield, Mylar/Dual-Foil Wrap, EMI Gasket, Pair Shields, foil-out, Ni-plated Backshell, and Insulator.

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